MB05M THRU MB10M

SINGLE PHASE 0.8AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

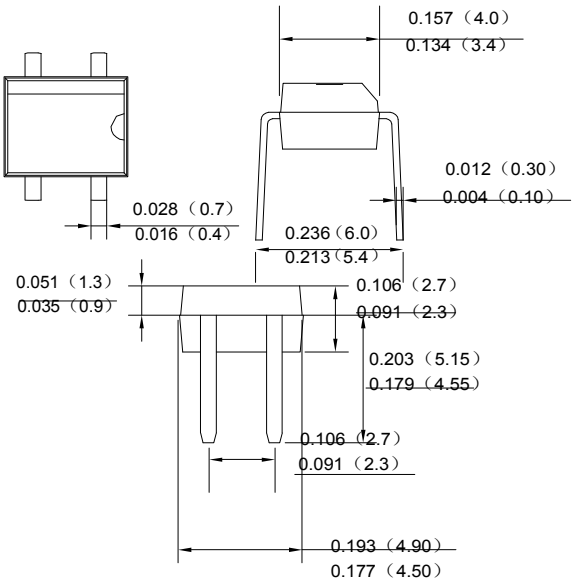
Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number

MBM



Dimiensions in inches and （milimeters）

Maximum Ratings and Electrical Characteristics

Rating at 25℃ ambient temperature unless otherwise specified.
Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	MB05M	MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T_A=40℃ (Note 2)@T_A=40℃	I_O	0.5 0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Forward Voltage per element @IF=0.8A	V_{FM}	1.1							V
Peak Reverse Current @T_A=25℃ At Rated DC Blocking Voltage @T_A=125℃	I_R	5.0 500							uA
Typical Junction Capacitance per leg	C_J	13							pF
Typical Thermal Resistance per leg (Note 3)	$R_{\theta JA}$ $R_{\theta JL}$	70 20							℃/W
Operating and Storage Temperature Range	T_J,T_{STG}	-55to+150							℃

Note:1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm^2 solder pad.
3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

GAIA TECH

MB05M THRU MB10M

Fig. 1 Output Current Derating Curve

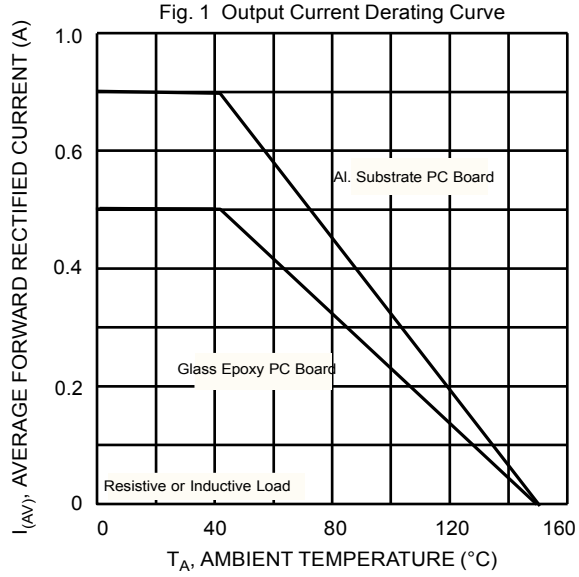


Fig. 2 Typical Forward Characteristics (per leg)

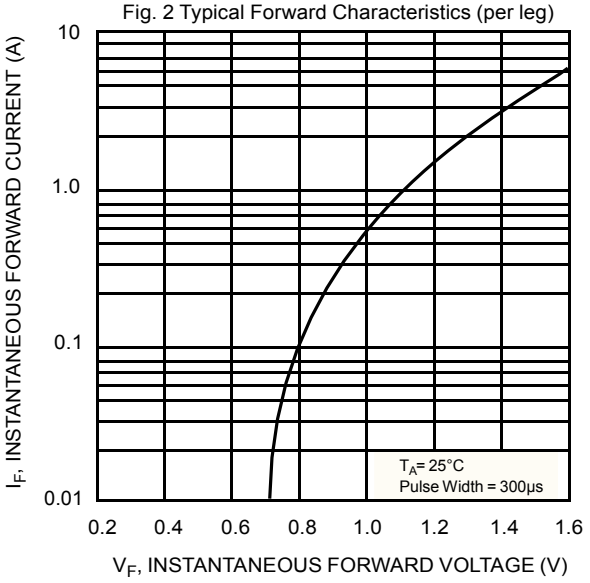


Fig. 3 Maximum Peak Forward Surge Current (per leg)

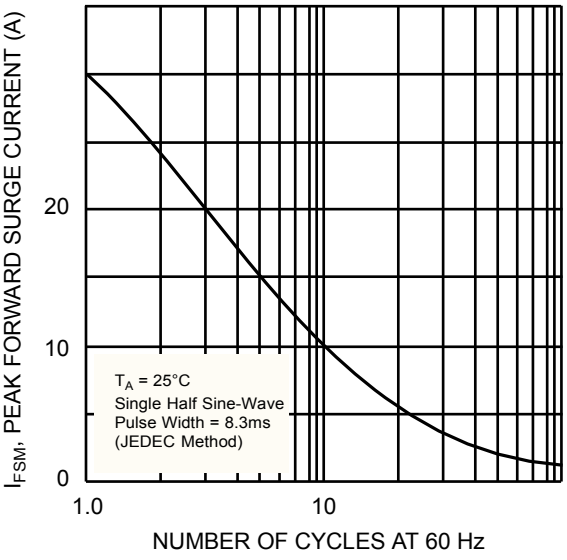


Fig. 4 Typical Junction Capacitance

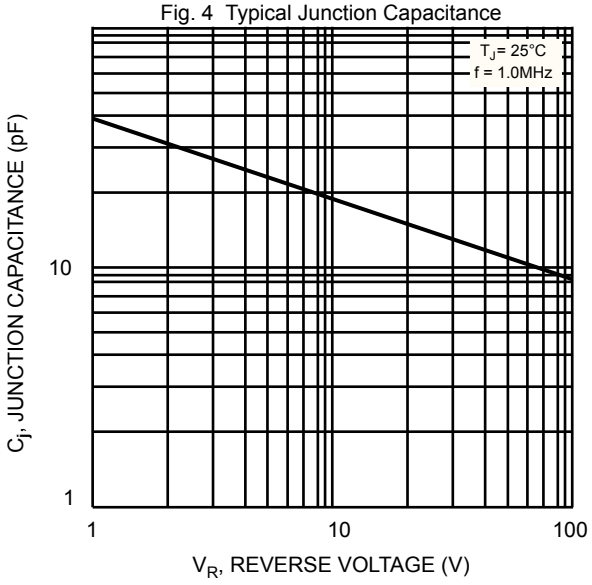


Fig. 5 T ypical Reverse Characteristics (per element)